SPECIFICATION

REFOND P/N

RF-A1T35-WYSE-A9

□R&D

■ Mass Production

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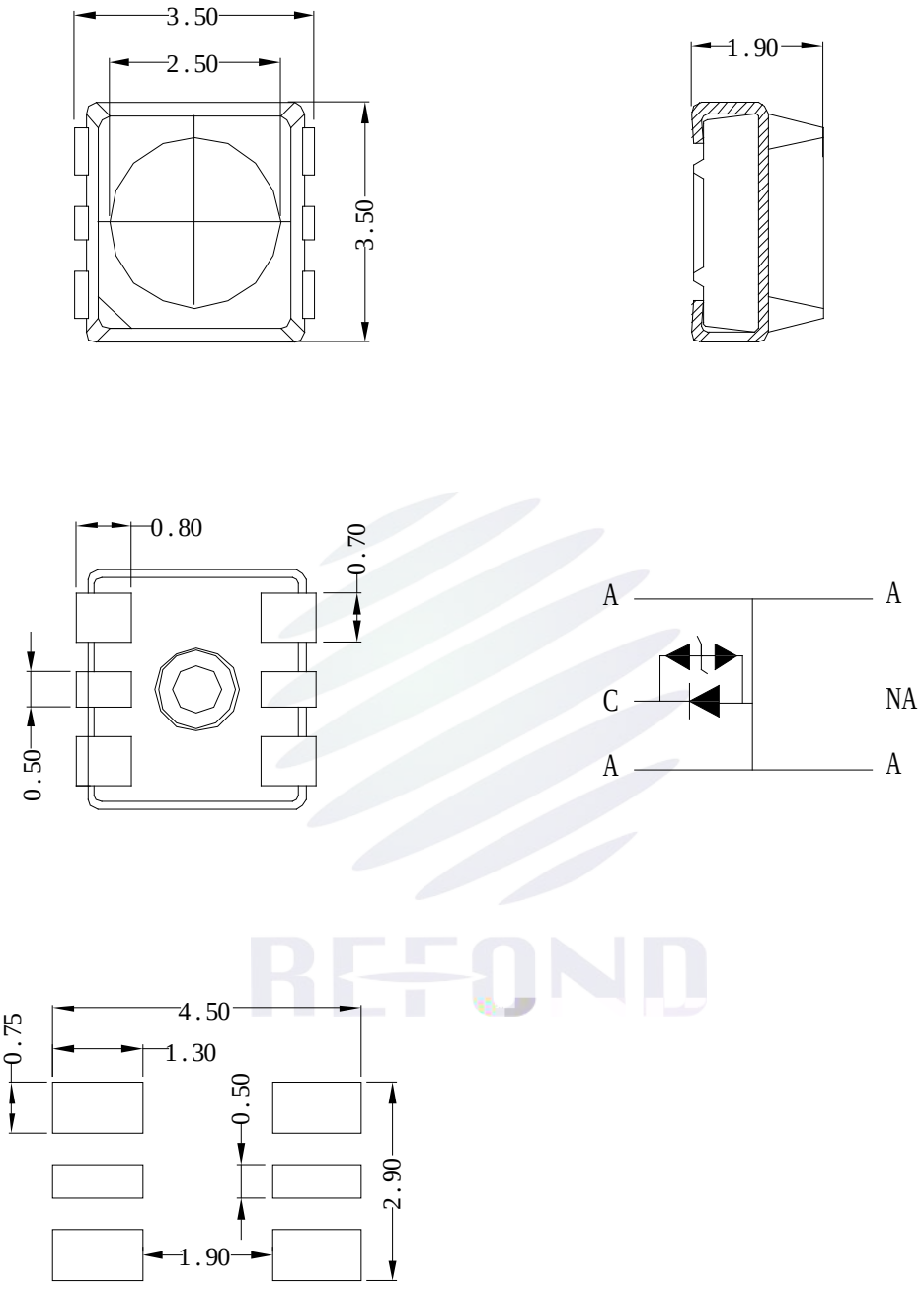
1.4Package Dimension



Notes

1. All dimensions units are millimeters.

2. All dimensions tolerances are ±0.05mm unless otherwise noted. ± 0.05

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1.5Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward Voltage	V_F	I_F=150mA	2.9	---	3.4	V
Reverse Current	I_R	V_R=5V	---	---	10	uA
Luminous Flux		I_F=150mA	40.9	---	55.3	lm
Viewing Angle		I_F=150mA	---	120	---	deg
Thermal Resistance (Junction to Solder)	Rth JS real	I_F=150mA	---	50	65	/W
	Rth JS el	I_F=150mA	---	30	40	/W

Table 1-2 Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	P_D	612	mW
Forward Current	I_F	180	mA
Peak Forward Current	I_{FP}	350	mA
Reverse Voltage	V_R	5	V
Electrostatic Discharge (HBM)	E_{SD}	8000	V
Operating Temperature	T_{OPR}	-40 ~ +110	
Storage Temperature	T_{STG}	-40 ~ +110	
Junction Temperature	T_J	125	

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Notes

1. 1/10 Duty cycle, 10ms pulse width. 10ms, 1/10.

2. The above forward voltage measurement allowance tolerance is ±0.1V. ± 0.1V.

3. The above color coordinates measurement allowance tolerance is ±0.005. ± 0.005.

4. The above luminous flux measurement allowance tolerance ±10%. ± 10%.

5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.

6. All measurements were made under the standardized environment of Refond.

7.When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED

8. ESD yield is over 90% at 8000V ESD (HBM). ESD protection during products handing is needed. 90% LED ESD8000V ,

9. At 25 test, photoelectric conversion efficiency ηe=49%. 25 49%

1.6Bin Range Of Forward Voltage and Luminous Flux (IF=150mA)

BIN (IF=150mA)

Table 1-3

V_F	G2	H1	H2	I1	I2
	2.9-3.0	3.0-3.1	3.1-3.2	3.2-3.3	3.3-3.4
lm	NB	OA	OB		
	40.9-45.3	45.3-50.0	50.0-55.3		

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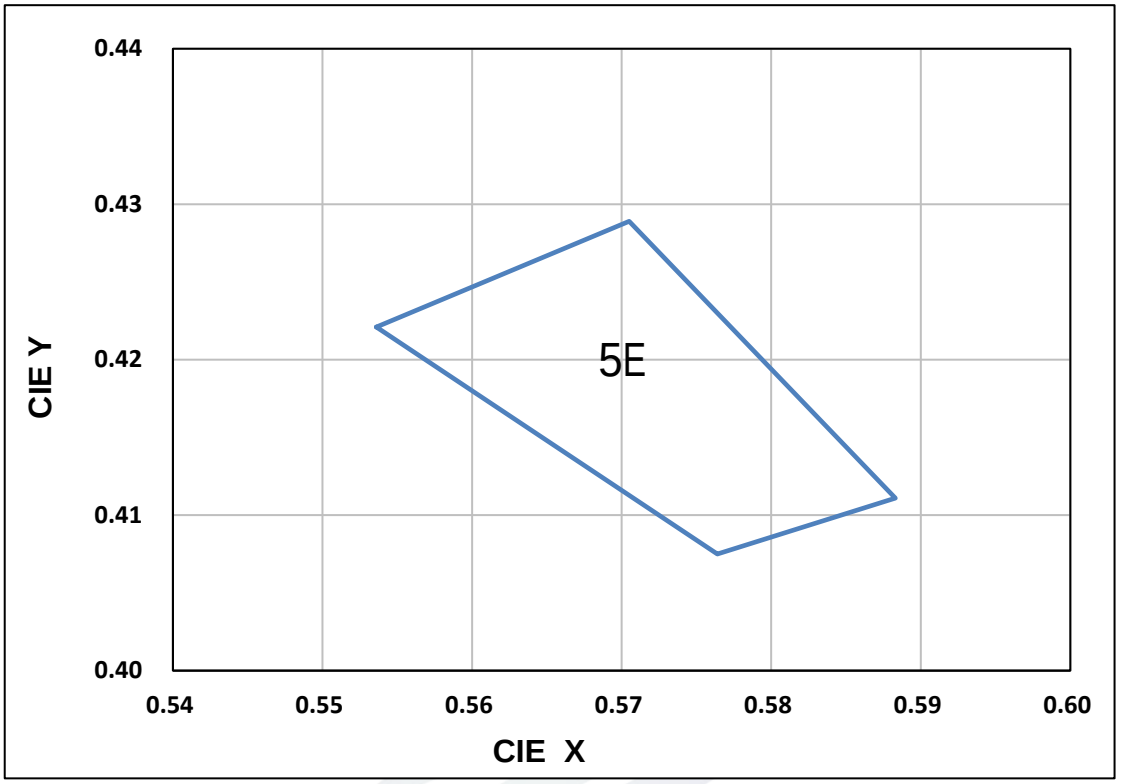

Fig 1-6 The C.I.E Chromaticity Diagram CIE

Table 1-4

BINCODE	CIE-X1	CIE-Y1	CIE-X2	CIE-Y2	CIE-X3	CIE-Y3	CIE-X4	CIE-Y4
5E	0.5536	0.4221	0.5764	0.4075	0.5883	0.4111	0.5705	0.4289

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1.7 Typical Optical Characteristics Curves

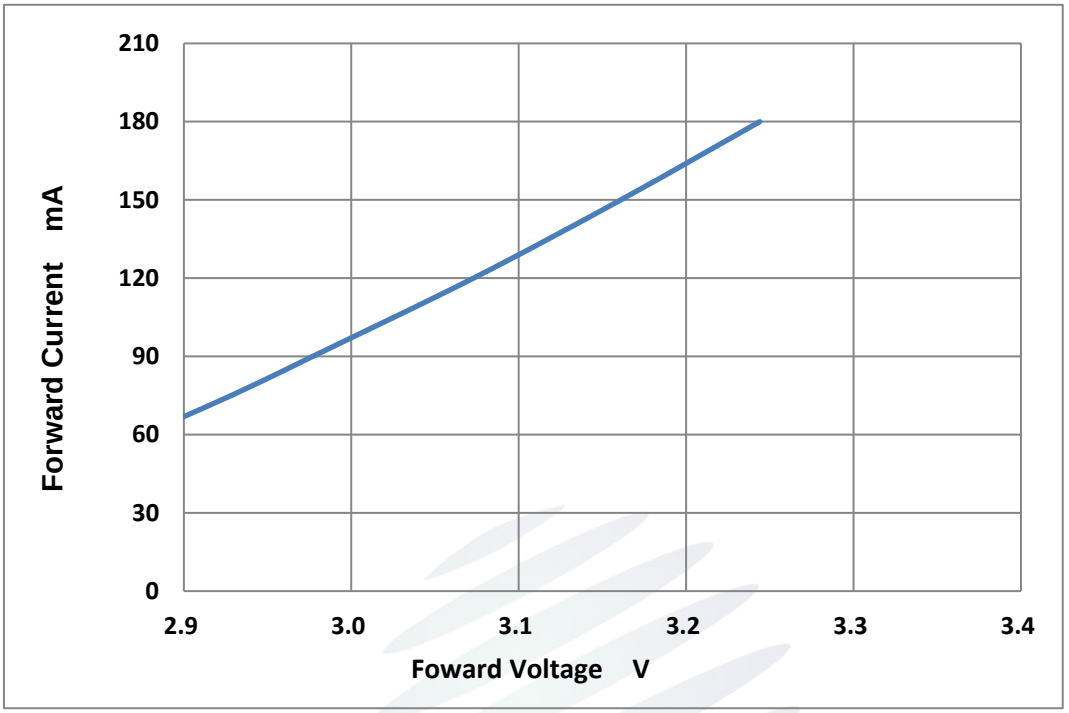

Fig. 1-7 Forward Voltage Vs Forward Current

Fig. 1-8 Forward Current Vs Relative Intensity

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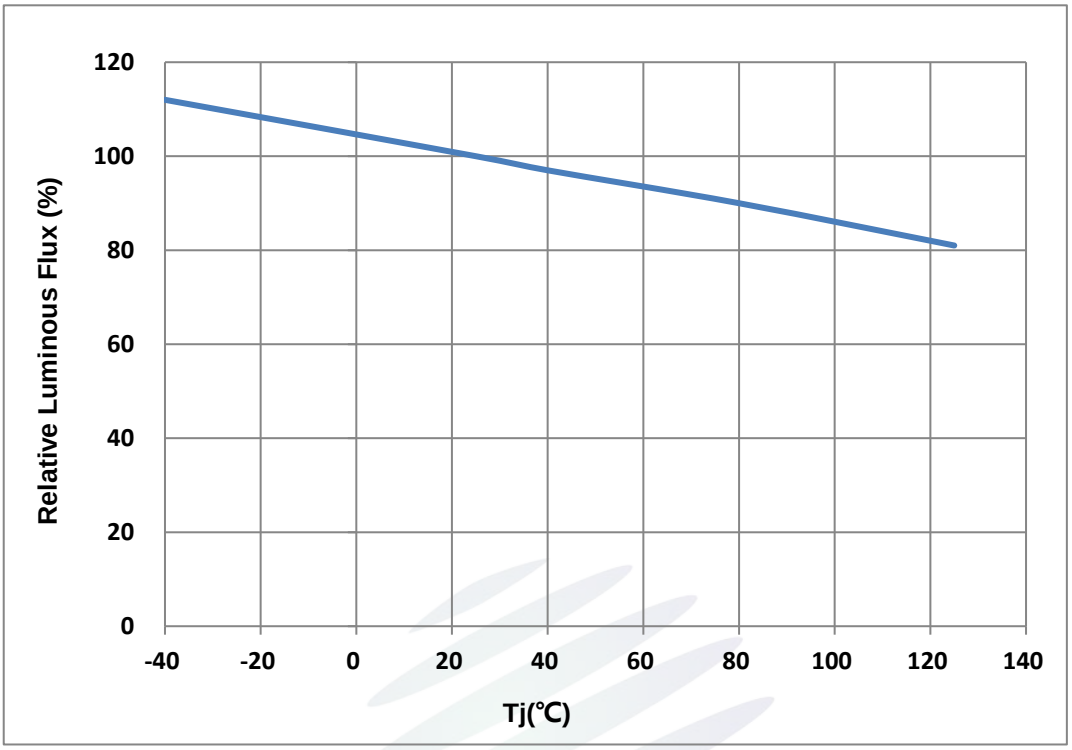

Fig. 1-9 Junction Temperature Vs Relative Intensity

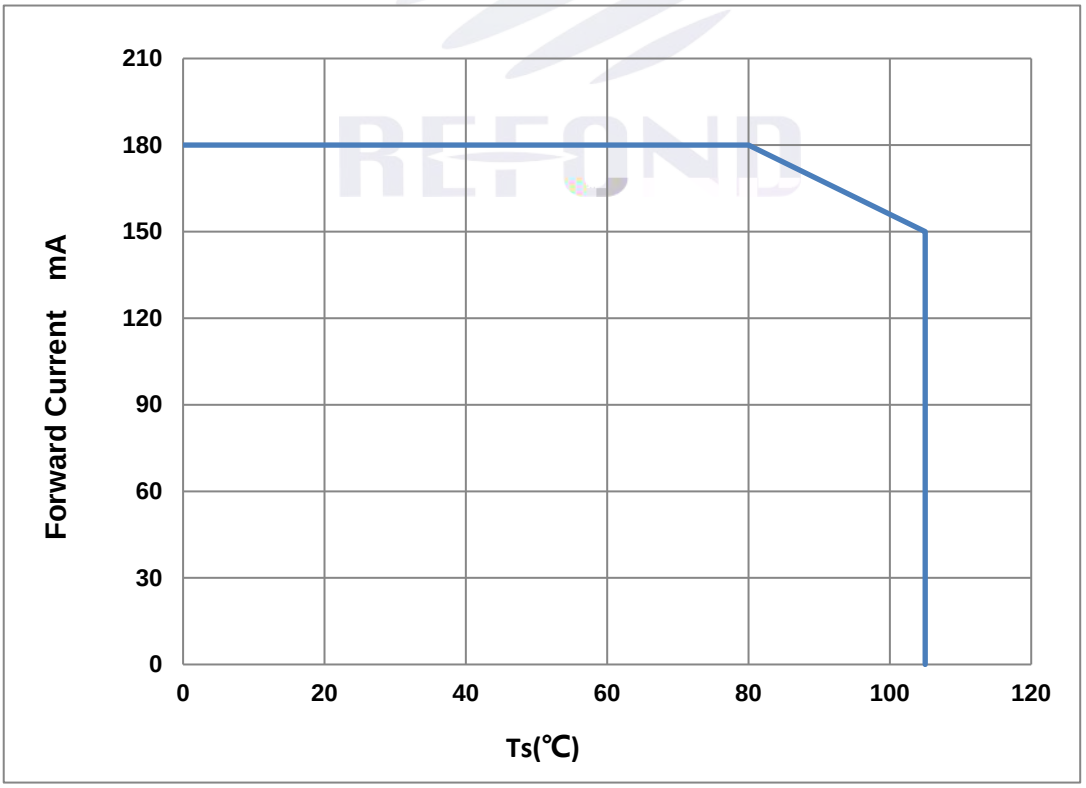

Fig. 1-10 Solder Temperature Vs Forward Current

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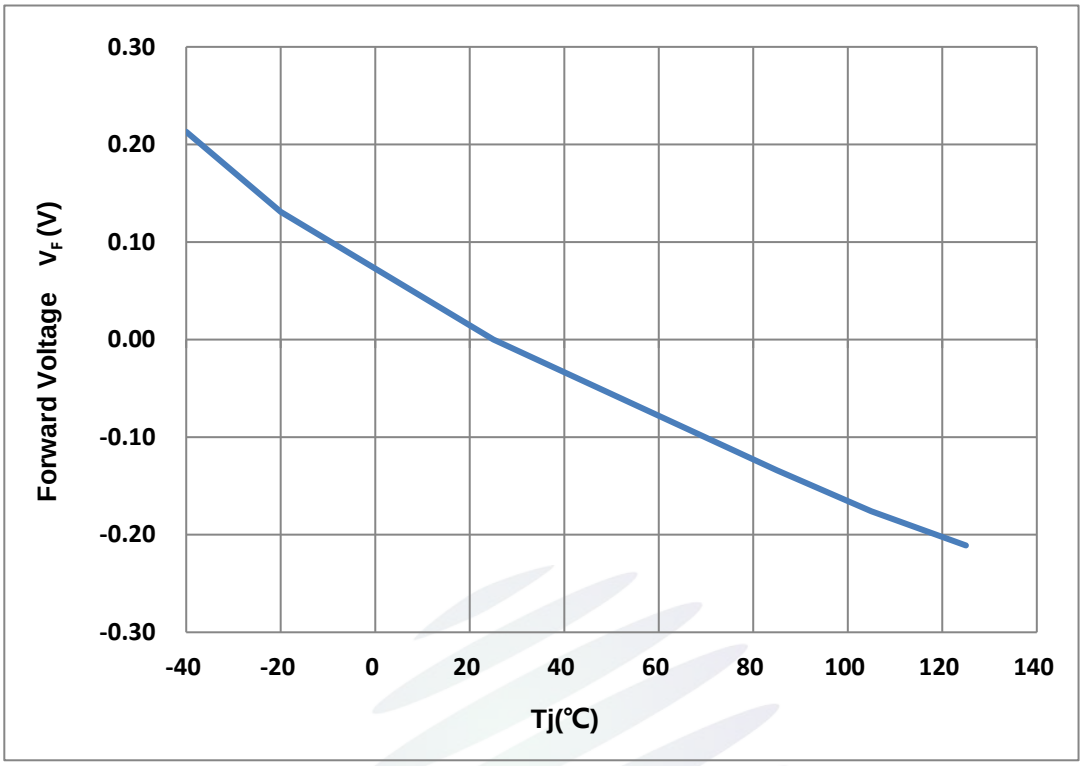

Fig. 1-11 Voltage Shift Vs Junction Temperature

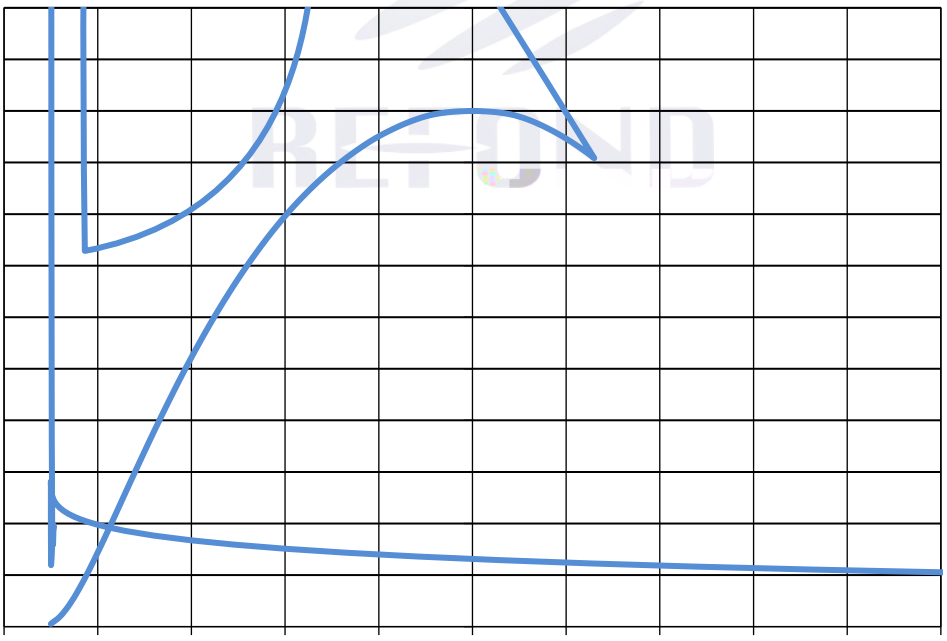

Fig. 1-12 Radiation diagram

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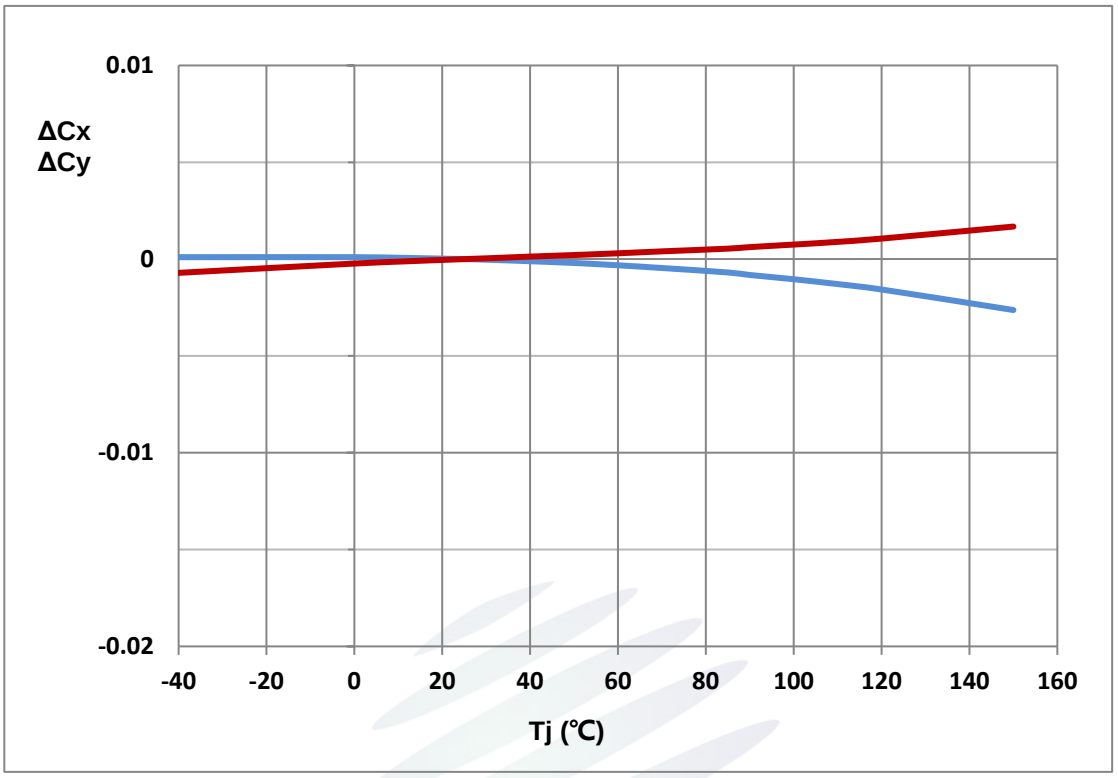

Fig. 1-13 Chromaticity Coordinate Vs Solder Temperature

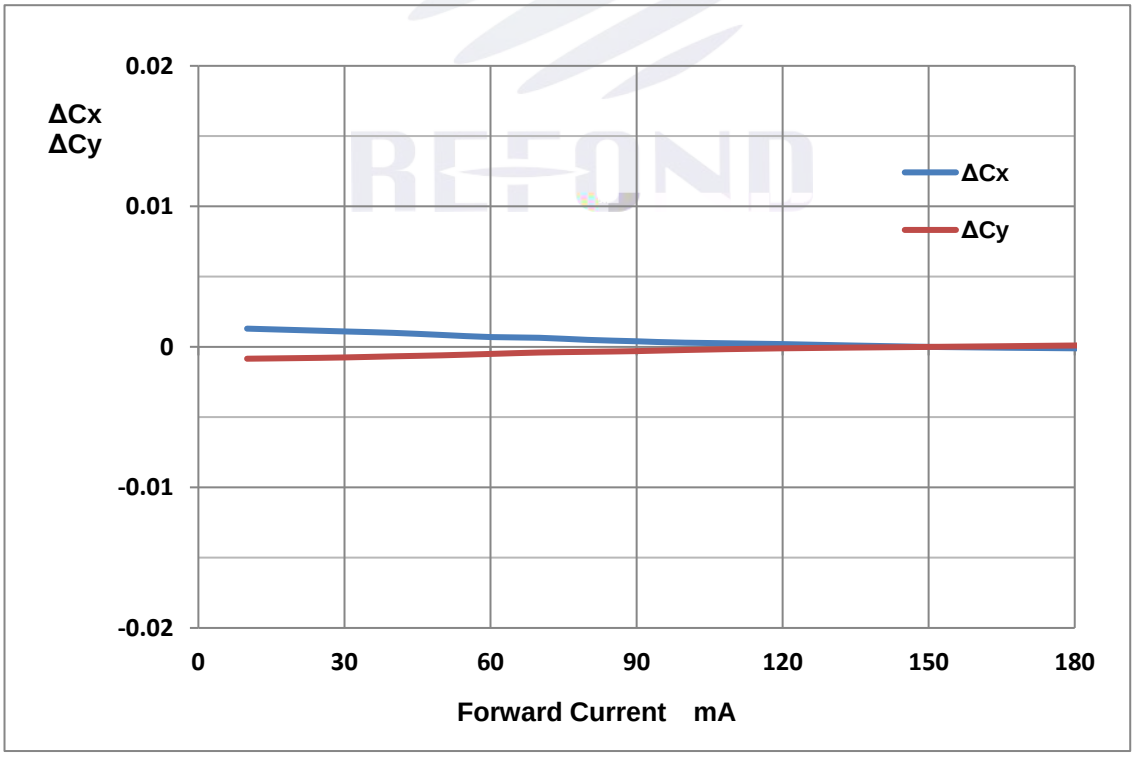

Fig. 1-14 Chromaticity Coordinate Shift Vs Forward Current

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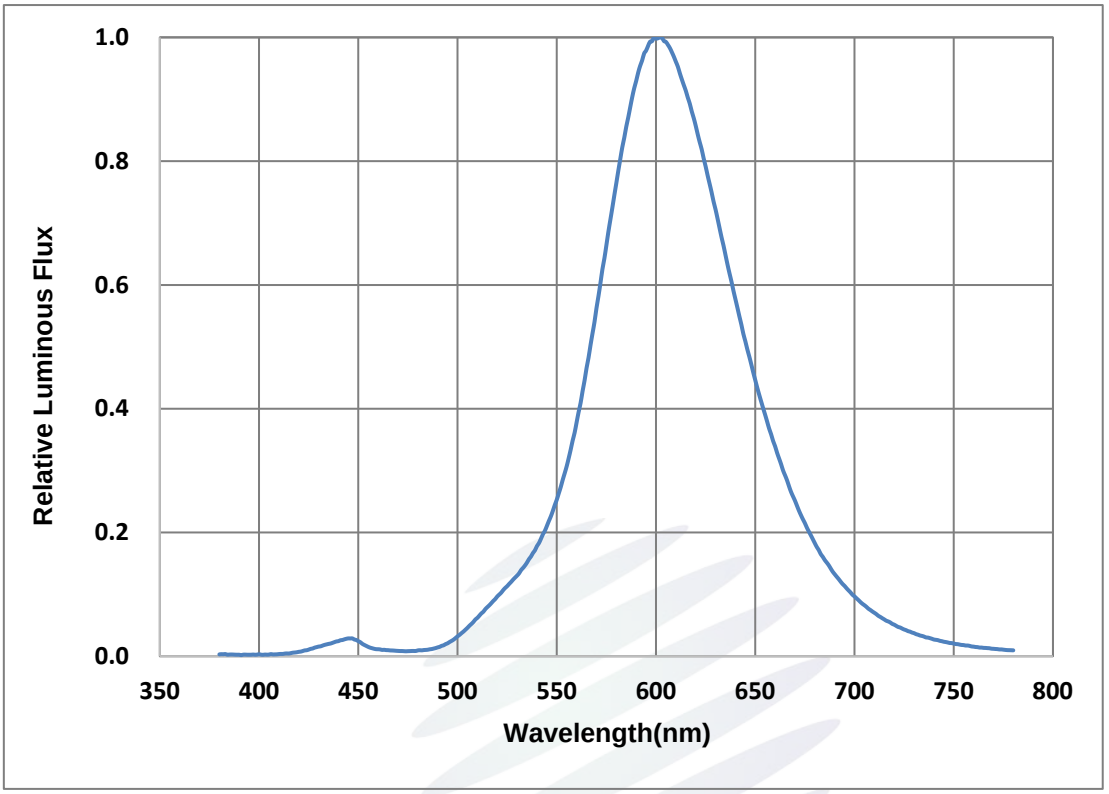

Fig. 1-15 Spectrum Distribution

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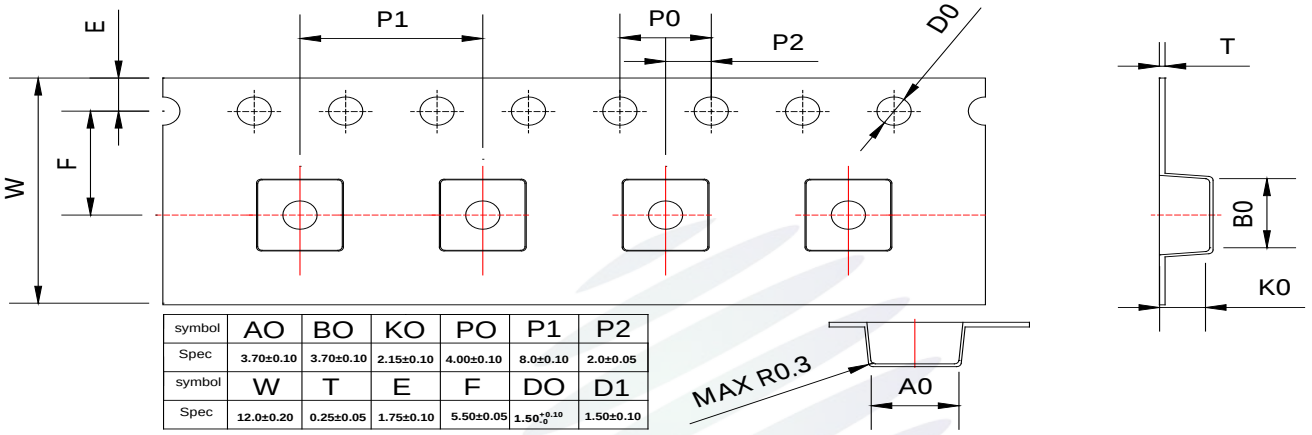
2. Packaging

2.1 Packaging Specification

Package:4000pcs/reel. 4000pcs

2.1.1Carrier Tape Dimension



symbol	AO	BO	KO	PO	P1	P2
Spec	3.70±0.10	3.70±0.10	2.15±0.10	4.00±0.10	8.0±0.10	2.0±0.05
symbol	W	T	E	F	DO	D1
Spec	12.0±0.20	0.25±0.05	1.75±0.10	5.50±0.05	$1.50^{+0.10}_{0}$	1.50±0.10

Fig.2-1 Carrier Tape Dimension

2.1.2Reel Dimension

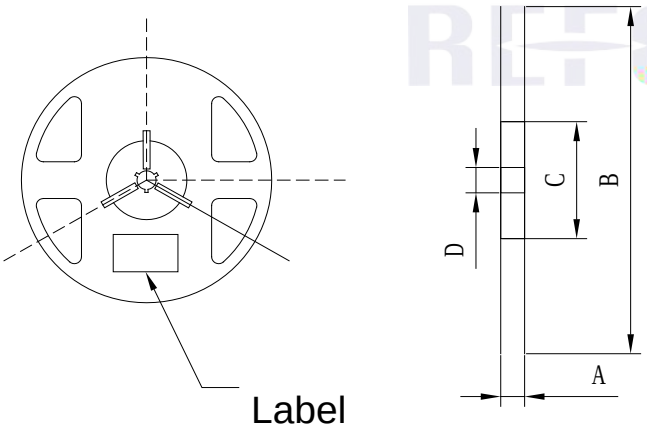


Fig.2-2Reel Dimension

Table 2-1Reel Dimension

A	12 ± 0.1mm
B	330 ± 1mm
C	100 ± 1mm
D	13.0 ± 0.5mm

Notes

The tolerances unless mentioned ±0.1mm. Unit : mm ± 0.1

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02 98 (02 98 (02 -Sub <616C -Su6 <652 -Sub <4072>TJ E<656664 07E<6F6E642E6 -Sub <6F6D393338.37618.9 288.84 56.7 re W n BT /C

2.4Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re /
Reflow	JESD22-B106	Temp:260 max T=10 sec	2times	20pcs.	0/1
MSL2 2	JESD22-A113	85 / 60%R_H	168 hrs.	20pcs.	0/1
Thermal Shock	JEITAED-4701 300307	-40 15min 10s 125 15min	1000 cycle	20pcs.	0/1
Life Test	JESD22-A108	Ta=105 I_F=150mA	1000hrs.	20pcs.	0/1
High Temperature High Humidity Life Test	JESD22-A101	85 / 85%R_H I_F=150mA	1000hrs.	20pcs.	0/1

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2.5 Criteria For Judging Damage

Table 2-4Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V_F	I_F=150mA	-	U.S.L*)x1.1
Reverse Current	I_R	V_R = 5V	-	U.S.L*)x2.0
Luminous Flux		I_F=150mA	L.S.L*)x0.7	-

Notes

1.U.S.L: Upper standard level L.S.L: Lower standard level

2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others. / LED

LED

3. The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.

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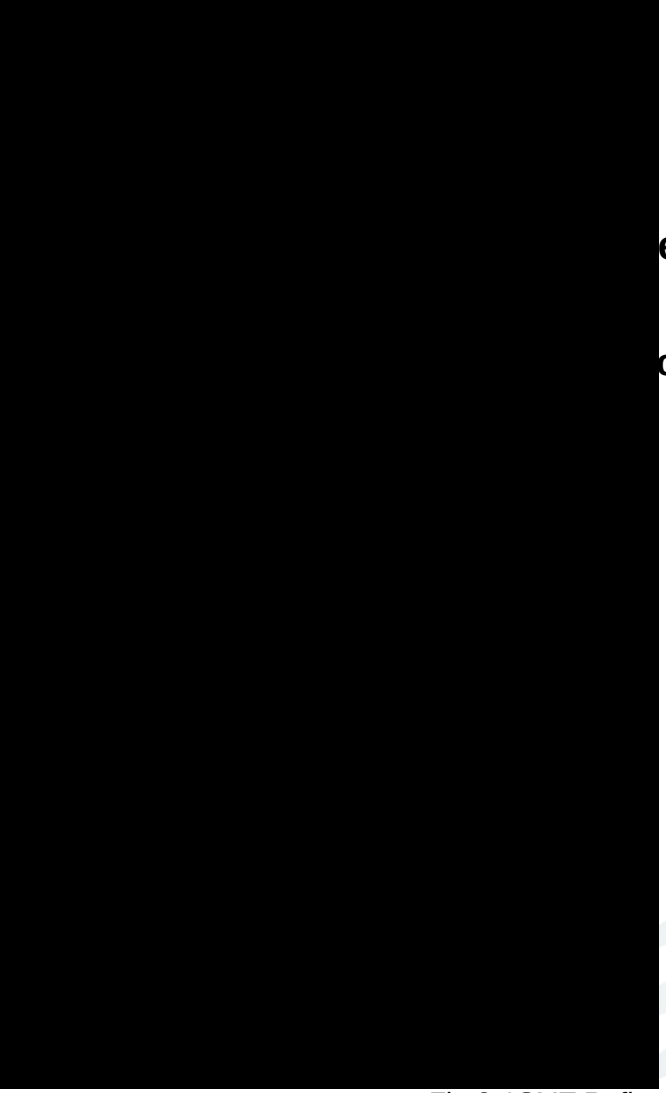

Fig.3-1SMT Reflow Soldering Instructions SMT

Table 3-1Reflow parameters

Average temperature rise speed Tsmax T_P	3 °C/ Max 3 °C/ s
Preheating: minimum temperature (Tsmin)	150 °C
Preheating: Max temperature (Tsmax)	200 °C
Preheating: Time Tsmin Tsmax	60 - 120 60s-120s
Time limited to maintain high temperature: the temperature (T_L)	217 °C
Time limited to maintain high temperature: The Time (t_L)	60 Max 60s
Peak /Classification of temperature: / (T_P)	260 °C

Time limit classification of peak temperature time t

ax 60s 260 °60G3

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Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings ,LED will be damaged. 24 LED

(2)When soldering , do not put stress on the LEDs during heating.

3.1.1 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED LED

3.1.2 Cautions

(1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper. LED LED

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED PCB

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

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4. Handling Precautions

4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement.LED

LED 100PPM.

(2) In order to prevent ex-ternal material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM,the single content of Chlorine elementis required to be less than 900PPM,the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement. LED LED

900PPM 900PPM

1500PPM.

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor. LED

LED LED

LED

(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

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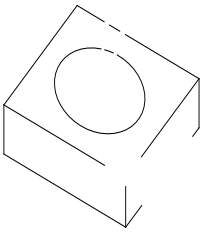

Fig 4-1Cautions

(5) In designing a circuit,the current through each LED can not exceed the absolute maximum rating specified for each LED.In the mean while,resistors for protection should be applied,other wise slight voltage shift will cause big current change,burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF.If the reverse voltage is applied to LED, migration can be generated resulting in LED damage. LED

LED

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline,such as brightness decreased,Color change and so on.Please consider the heat generation of the LEDs when making the system design.LED LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust,requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

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Version History/

Date	Revisor	Version	Verifier	Remarks
2022/01/15	Lu Xian	E0	Zhu yiming	New issue
2023/3/14	Ruan Minghui	E1	Zhu yiming	Template update

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Declare

This specification is written both in English and in Chinese and the latter is formal.

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